

ABSTRACT OF THE DISCLOSURE

A circuit package with improved heat dissipation properties for high-power circuits. In one embodiment, the circuit package comprises two circuit boards positioned in different planes, at least one brace affixed between the two circuit boards, a molded housing enclosing an area between the circuit boards, and a plurality of electrically conductive leads extending from the sides of the circuit package. The molded housing is configured to expose at least one surface of the circuit boards to the exterior surface of the circuit package. The leads are configured in a J-shape, which allows the circuit package to be mounted in an upright position. The brace functions as a flexible spacer for holding the two circuit boards in position during the application of the molded housing. In one embodiment, a H-bridge circuit is configured on the first and second circuit boards of the circuit package.

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